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About this book. Edited by key figures in 3d integration and written by top authors from high-tech companies and renowned research institutions, this book covers the intricate details of 3D process technology. As such, the main focus is on silicon via formation, bonding and debonding, thinning, via reveal and backside processing, both from a technological and a materials science perspective.

Handbook of 3D Integration | Wiley Online Books

Handbook of 3D Integration, Volumes 1 and 2: Technology and Applications of 3D Integrated Circuits. 1st Edition. by Philip Garrou (Editor), Christopher Bower (Editor), Peter Ramm (Editor) & 0 more. ISBN-13: 978-3527332656. ISBN-10: 9783527332656.

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This two-volume handbook presents 3D solutions to the feature density problem, addressing all important issues, such as wafer processing, die bonding, packaging technology, and thermal aspects. It begins with an introductory part, which defines necessary goals, existing issues and relates 3D integration to the semiconductor roadmap of the industry.

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James J. Q. Lu, Dingyou Zhang, Peter Ramm, Overview of Bonding and Assembly for 3D Integration, Handbook of 3D Integration, 10.1002/9783527670109, (261-278), (2014). ... Handbook of 3D Integration: Technology and Applications of 3D Integrated Circuits. Related; Information; Close Figure Viewer. Return to Figure. Previous Figure Next Figure.

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Handbook of 3D Integration, Volume 3: 3D Process Technology

An essential part of successfully introducing a new technology is to educate engineers and managers on its benefits and tradeoffs. That ' s why Wiley started publishing the Handbook of 3D Integration Series with Volume 1 and 2 in 2008, followed by Volume 3 in 2014. This blog covers Volume 4, introduced in early May 2019.